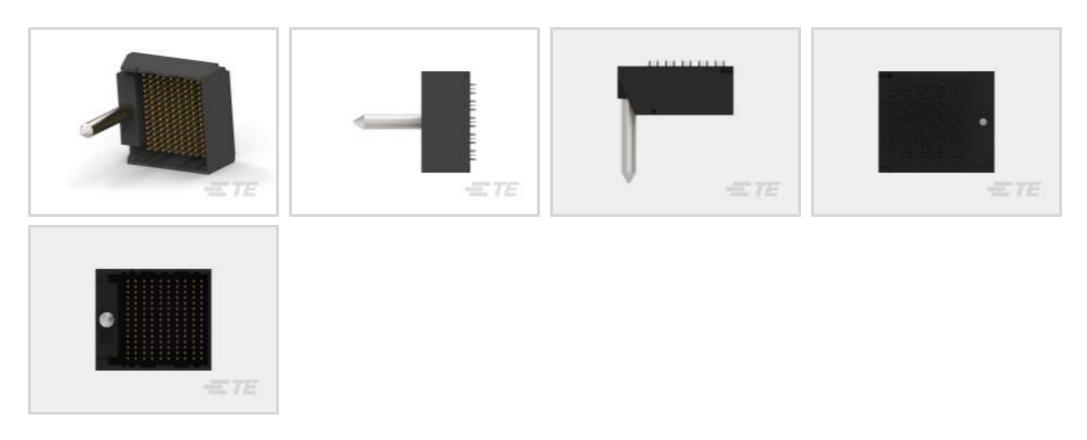


#### IMPACT

TE Internal #: 2143558-2 High Speed Backplane Connectors, 150 Position, Mating Alignment, Guide Pin Mating Alignment Type, 15 Row, 10 Column, PCB Mount Header, IMPACT

#### View on TE.com >

Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors



Connector System: Board-to-Board Number of Positions: 150 Row-to-Row Spacing: 1.15 mm [.045 in ] Mating Alignment: With

Mating Alignment Type: Guide Pin

# Features



### Product Type Features

Signal Arrangement	Differential	
Connector System	Board-to-Board	
PCB Connector Assembly Type	PCB Mount Header	
Shroud Style	Fully Shrouded	
Connector & Contact Terminates To	Printed Circuit Board	
Configuration Features		
Number of Ground Positions	50	
Number of Pairs	50	
Stackable	No	
Number of Signal Positions	100	
Backplane Architecture	Orthogonal	
Number of Positions	150	
Number of Rows	15	
Number of Columns	10	

High Speed Backplane Connectors, 150 Position, Mating Alignment, Guide Pin Mating Alignment Type, 15 Row, 10 Column, PCB Mount Header, IMPACT



PCB Mount Orientation	Vertical	
Guide Location	Left	
Electrical Characteristics		
Impedance	100 Ω	
Operating Voltage	30 VAC	
Signal Characteristics		
Number of Differential Pairs per Column	5	
Data Rate	20 – 25 Gb/s	
Body Features		
Primary Product Color	Black	
Contact Features		
Contact Mating Area Length	5.5 mm[.217 in]	
PCB Contact Termination Area Plating Material Thickness	.76 – 1.52 μm[30 – 60 μin]	
Contact Layout	Inline	
Contact Type	Pin	
Contact Underplating Material Thickness	1.27 μm[50 μin]	
Contact Mating Area Plating Material Thickness	.76 μm[29.92 μin]	
Contact Mating Area Plating Material	Gold	
PCB Contact Termination Area Plating Material Finish	Matte	
Contact Shape & Form	Dual Beam	
Contact Underplating Material	Nickel	
PCB Contact Termination Area Plating Material	ting Material Tin	
Contact Base Material	Copper Alloy	
Contact Current Rating (Max)	.75 A	
Termination Features		
Termination Post & Tail Length	1.4 mm[.055 in]	
Termination Method to Printed Circuit Board	Through Hole - Press-Fit	
Mechanical Attachment		
PCB Mount Alignment Type	Locating Posts	
Guide Hardware	With	
Mating Retention Without		
PCB Mount Retention	With	

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PCB Mount Retention Type	Action/Compliant Tail & Screw		
Mating Alignment	With		
Mating Alignment Type	Guide Pin		
Connector Mounting Type	Board Mount		
Housing Features			
Number of Shrouded Sides	3		
End Wall Location	Right		
Housing Material	LCP (Liquid Crystal Polymer)		
Centerline (Pitch)	1.9 mm[.075 in]		
Dimensions			
Connector Length	28.4 mm[1.118 in]		
Connector Height	11.95 mm[.47 in]		
Connector Width	24.8 mm[.976 in]		
PCB Thickness (Recommended)	3 mm[1.118 in]		
PCB Hole Diameter	.39 mm[.015 in]		
Row-to-Row Spacing	1.15 mm[.045 in]		
Usage Conditions			

O	perating	Tempe	erature	Range
				0

-55 – 85 °C[-67 – 185 °F]

# **Operation/Application**

Circuit Application	Signal
Industry Standards	
Approved Standards	CSA Certified, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box & Tube, Package
Product Compliance	
For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	

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Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

#### Halogen Content

#### Solder Process Capability

Not reviewed for solder process capability

#### Product Compliance Disclaimer

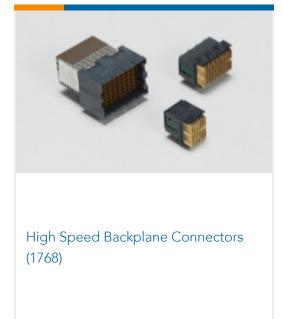
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# **Compatible Parts**



TE Part # 2132695-1 IMP100O,R,RA5P10C,UG,39

# Also in the Series | IMPACT

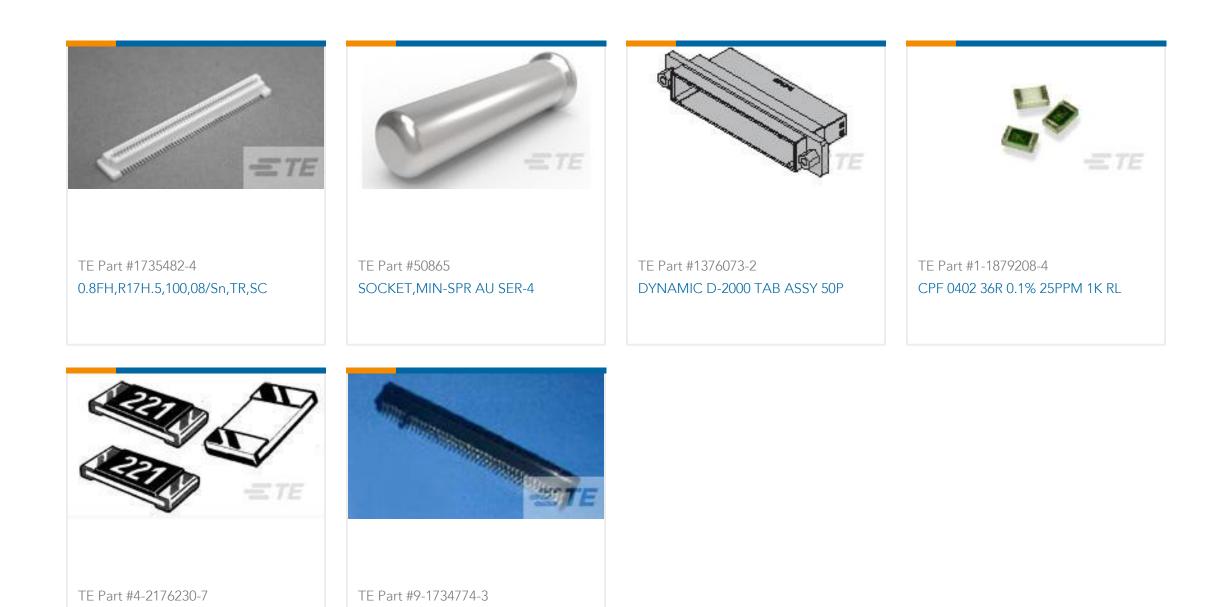


# **Customers Also Bought**

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PCI EXP 2.3L 64 POS BLK 30u"

# Documents

3522 5K6 5% 3W

Product Drawings IMP100O,HMP,V5P10C,LG,REW39,5.5

English

CAD Files

3D PDF

3D

Customer View Model ENG\_CVM\_CVM\_2143558-2\_D.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2143558-2\_D.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_2143558-2\_D.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English

Agency Approvals Agency Approval Document

English